



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-19
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA7576B	I8V2*UK24BB1	A	BO2A	2016-05-19
Amount	UoM	Unit type	ST ECOPACK Grade	
5700.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	20x10.7x4.5	15	Through-hole	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	true
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th Dec 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IBV2*UK248B1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	14.641	mg	supplier	die	Silicon (Si)	7440-21-3		13.740	mg	938460	2411
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.121	mg	8264	21
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.192	mg	13114	34
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.029	mg	1981	5
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.284	mg	19398	50
Die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.011	mg	751	2
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.028	mg	1912	5
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.094	mg	6420	16
Die				supplier	polymer die coating	PIX1 Gamima-butylolactone	96-48-0		0.142	mg	9699	25
Leadframe	Copper & its alloys	4446.546	mg	supplier	alloy	Copper (Cu)	7440-50-8		4417.766	mg	993528	775047
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		2.035	mg	458	357
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		3.716	mg	836	652
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		18.690	mg	4203	3279
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		4.339	mg	976	761
Die attach		9.661	mg	JIG - R	Soft Solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	9.419	mg	974951	1652
Die attach				supplier	Soft Solder	Silver (Ag)	7440-22-4		0.145	mg	15009	25
Die attach				supplier	Soft Solder	Tin (Sn)	7440-31-5		0.097	mg	10040	17
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		1.665	mg	1000000	292
encapsulation		1198.061	mg	supplier	mold compound	Silica, vitreous	60676-86-0		859.011	mg	717001	150704
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		203.670	mg	170000	35732
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		86.260	mg	72000	15133
encapsulation				supplier	mold compound	Brominated epoxy resin	40039-93-8		17.971	mg	15000	3153
encapsulation				supplier	mold compound	Bismuth	7440-69-9		3.594	mg	3000	631
encapsulation				supplier	mold compound	Carbon black	1333-86-4		3.594	mg	3000	631
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		23.961	mg	20000	4204
connections coating	Solder	29.426	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		29.426	mg	1000000	5162